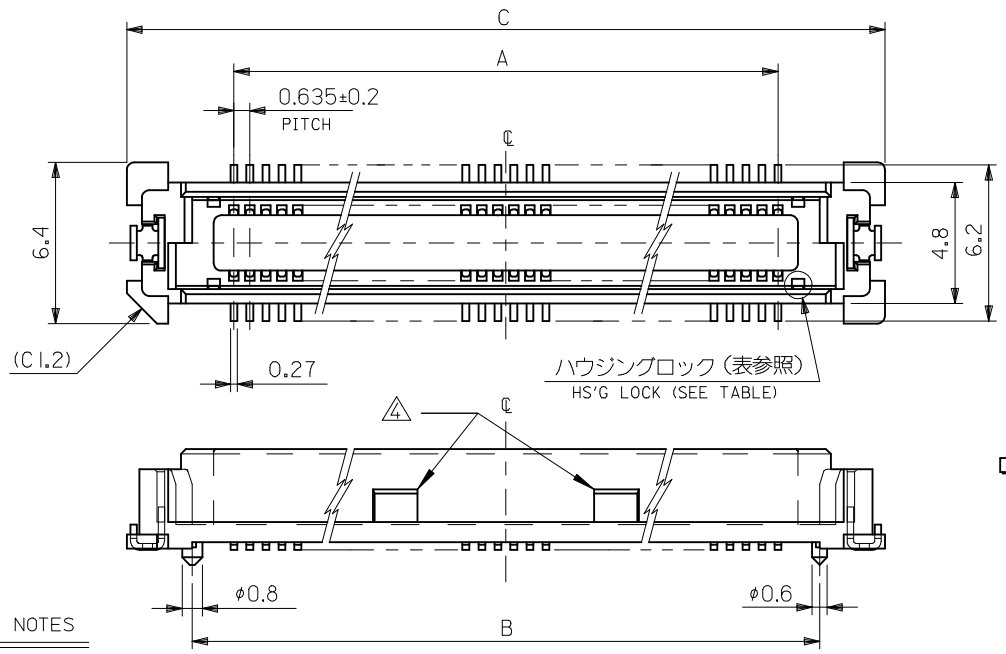
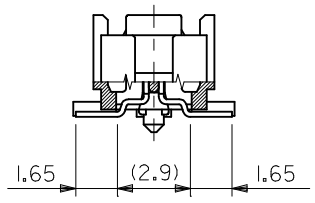
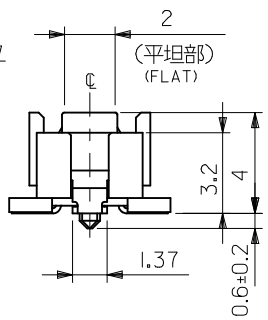
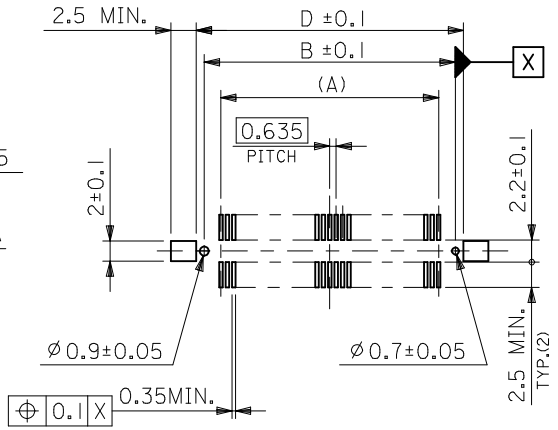




半田付け部詳細図
DETAIL FOR SOLDERING AREA





推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE:2-1)

注記 NOTES

1. 材質
MATERIAL
ハウジング ：ガラス入り LCP 、白色、UL94V-0
HOUSING: G.F.LCP ,WHITE ,UL94V-0
ターミナル ：銅合金 (t=0.2)
TERMINAL:COPPER ALLOY
ネイル ：銅合金 (t=0.25)
NAIL:COPPER ALLOY

2. メッキ仕様
PLATING
ターミナル： 接点部 ：金メッキ 0.25 μm MIN.
TERMINAL： CONTACT AREA; GOLD 0.25 MICROMETER MIN.
半田付け部 ：錫メッキ 2.0 μm MIN.
SOLDER TAIL AREA; TIN 2.0 MICROMETER MIN.
下地メッキ ：ニッケルメッキ 2.0 μm MIN.
UNDER-PLATING：NICKEL 2.0 MICROMETER MIN.
補強金具： 錫メッキ 1.0 μm MIN.
FITTING NAIL： TIN 1.0 MICROMETER MINIMUM
下地メッキ ：ニッケルメッキ 1.0 μm MIN.
UNDER-PLATING：NICKEL 1.0 MICROMETER MIN.

3. 200極以下のテール平坦度は 0.1 MAX. 、
TAIL COPLANARITY TO BE 0.1 MAX.
240極のテール平坦度は 0.12 MAX. とする.
IN 240 CIRCUITS, TAIL COPLANARITY TO BE 0.12 MAX.

△4 本製品は 2016 年 6 月 30日まで形状変更期間中となります.
THIS PRODUCT IS DURING A FORM CHANGE PERIOD TILL JUNE 30, 2016.
その為、図示形状が無い場合もございますが、製品機械性能上問題ございません.
THEREFORE, THERE MAY NOT BE THE ILLUSTRATED SHAPE.
HOWEVER, IT DOSE NOT AFFECT ON CONNECTOR MECHANICAL PERFORMANCE.

10 mm	53553 SERIES
9 mm	53552 SERIES
8 mm	53551 SERIES
7 mm	53481 SERIES
6 mm	53467 SERIES
5 mm	53475 SERIES
基板間寸法 STACKING HEIGHT	嵌合相手 TO BE MATED WITH

WITHOUT HSG LOCK	80.47	84.07	78.87	75.565	—	52760-2479	240
	67.77	71.37	66.17	62.865	—	52760-2079	200
	61.42	65.02	59.82	56.515	—	52760-1879	180
	55.07	58.67	53.47	50.165	—	52760-1679	160
WITH HSG LOCK	23.32	26.92	21.72	18.415	52760-0678	—	60
	20.15	23.75	18.55	15.24	52760-0578	52760-0579	50
	D	C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	STICK PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. : 52760-**70

REVISED
EC NO: J2017-0575 2017/05/15
DRWN:GES
CHKD:
APPR:MSASAO 2017/06/29
DESCRIPTION
REV
D

GENERAL TOLERANCES (UNLESS SPECIFIED)

0.25	UNDER	UNDER	±0.03
0.25	OVER 0.5	UNDER	±0.05
0.5	OVER 1.0	UNDER	±0.1
1.0	OVER 10	UNDER	±0.2
10	OVER 30	UNDER	±0.25
30	OVER		±0.3
ANGULAR	±3 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

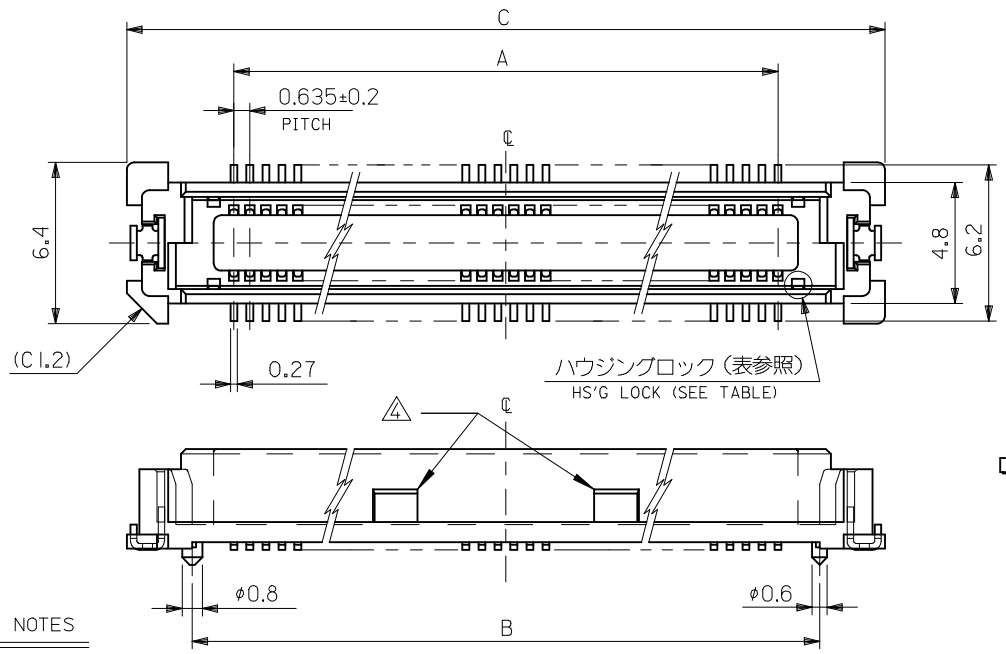
DRAWN BY: Y.WADA DATE: '04/02/26
CHECKED BY: M.SASAO DATE: '04/02/26
APPROVED BY: M.SASAO DATE: '04/02/26

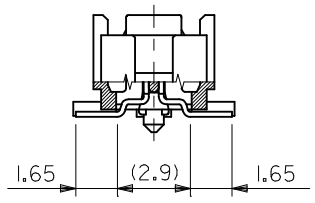
TITLE: 0.635 PITCH B-TO-B S/T REC. HSG ASSY -LEAD FREE-

molex

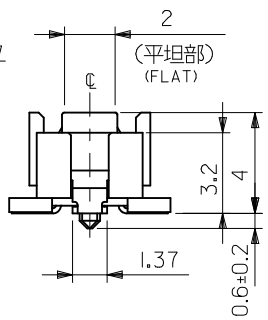
MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-52760-013
SHEET NO.: 1 OF 1
SIZE: A3

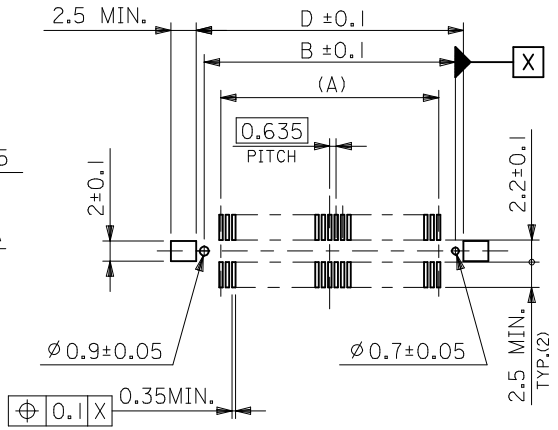
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半田付け部詳細図
DETAIL FOR SOLDERING AREA





推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE:2-1)

注記 NOTES

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MATERIAL
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PLATING
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TERMINAL： CONTACT AREA; GOLD 0.25 MICROMETER MIN.
半田付け部 ：錫メッキ 2.0 μm MIN.
SOLDER TAIL AREA; TIN 2.0 MICROMETER MIN.
下地メッキ ：ニッケルメッキ 2.0 μm MIN.
UNDER-PLATING：NICKEL 2.0 MICROMETER MIN.
補強金具： 錫メッキ 1.0 μm MIN.
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CONNECTOR SERIES No. : 52760-**70

REVISED
EC NO: J2017-0575 2017/05/15
DRWN:GES
CHKD:
APPR:MSASAO 2017/06/29
DESCRIPTION
REV
D

GENERAL TOLERANCES (UNLESS SPECIFIED)

0.25	UNDER	UNDER	±0.03
0.25	OVER 0.5	UNDER	±0.05
0.5	OVER 1.0	UNDER	±0.1
1.0	OVER 10	UNDER	±0.2
10	OVER 30	UNDER	±0.25
30	OVER		±0.3
ANGULAR	±3 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

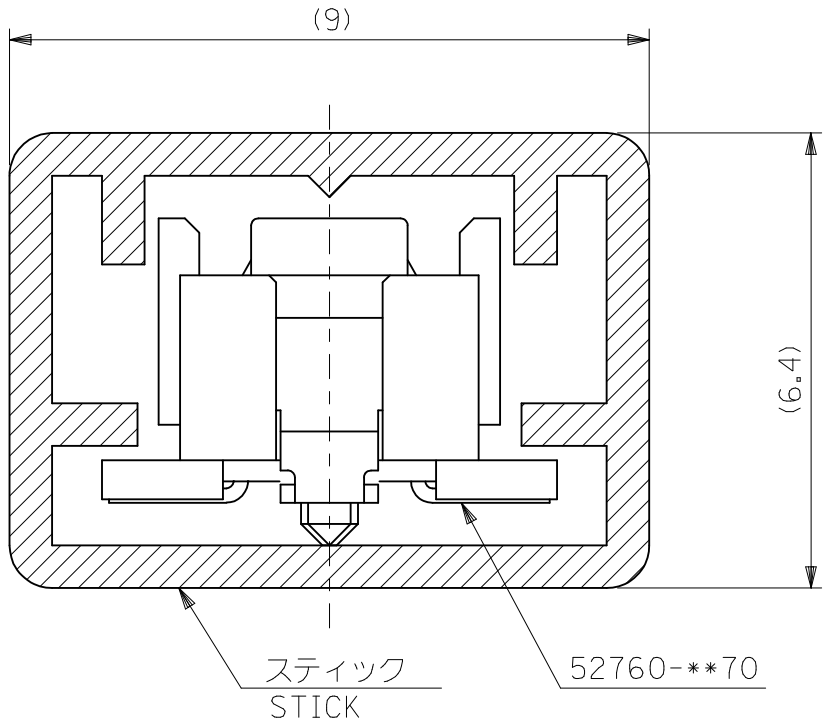
DRAWN BY: Y.WADA DATE: '04/02/26
CHECKED BY: M.SASAO DATE: '04/02/26
APPROVED BY: M.SASAO DATE: '04/02/26

TITLE: 0.635 PITCH B-TO-B S/T REC. HSG ASSY -LEAD FREE-

molex

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-52760-013
SHEET NO.: 1 OF 1
SIZE: A3

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注)
NOTES.

1. スティック両端はキャップ止め。
   BOTH ENDS WITH CAPS.
2. 全長： 600±2
   TOTAL LENGTH
3. 肉厚：0.6±0.2
   THICKNESS
4. 量産対応済の極数については、
   SD-52760-013 を参照下さい。
   SEE SD-52760-013 FOR AVAIRABLE ITEMS.
5. 本製品は５２７６０－＊＊＊９の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE OF 52760-***9.

6	52760-2479	240
7	-2079	200
8	-1879	180
9	-1679	160
23	52760-0579	50
梱包数 QUANTITY	MATERIAL NO.	極数 NO. OF CKT.

REVISED
EC NO: J2017-0575 2017/05/15
DRWN:GES
CH'KD:
APPR:MSASAO 2017/06/29
DESCRIPTION
A
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

0.25	UNDER		±
0.25	OVER	0.5 UNDER	±
0.5	OVER	1.0 UNDER	±
0	OVER	10 UNDER	±0.2
10	OVER	30 UNDER	±0.25
30	OVER		±0.3
ANGULAR	±3 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: Y.WADA DATE: 2004/02/26
CHECKED BY: M.SASAO DATE: 2004/02/26
APPROVED BY: M.SASAO DATE: 2004/02/26
MATERIAL NO.: SEE CHART

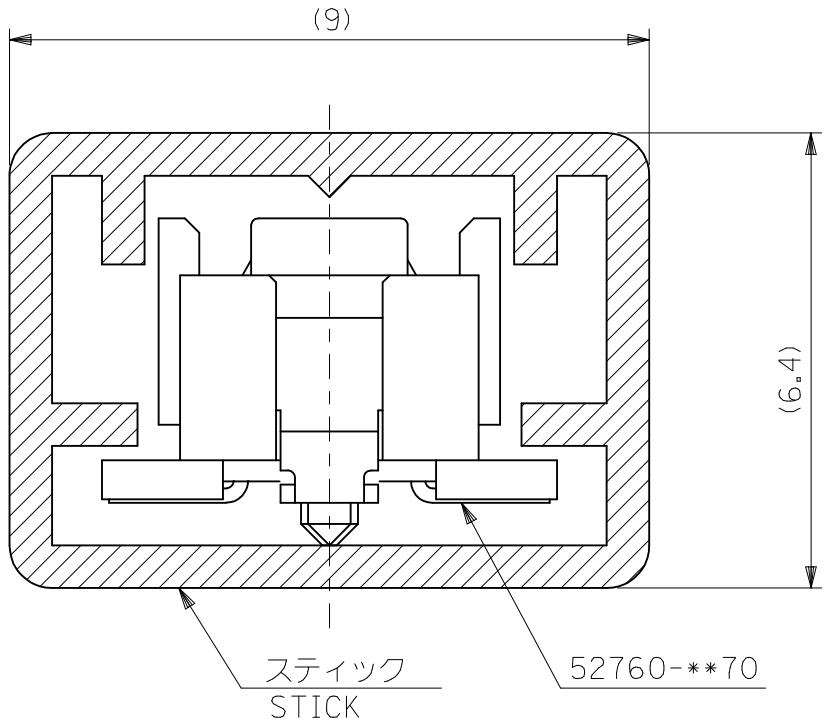
TITLE
52760-**70
STICK PACKAGING
-LEAD FREE-

molex

DOCUMENT NO.: SD-52760-015
SHEET NO.: 1 OF 1

SIZE A4

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7	-2079	200
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梱包数 QUANTITY	MATERIAL NO.	極数 NO. OF CKT.

REVISED
EC NO: J2017-0575 2017/05/15
DRWN:GES
CH'KD:
APPR:MSASAO 2017/06/29
DESCRIPTION
A
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

0.25	UNDER		±
0.25	OVER	0.5 UNDER	±
0.5	OVER	1.0 UNDER	±
0	OVER	10 UNDER	±0.2
10	OVER	30 UNDER	±0.25
30	OVER		±0.3
ANGULAR	±3 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

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DESIGN UNITS: METRIC
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DRAWN BY: Y.WADA DATE: 2004/02/26
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TITLE
52760-**70
STICK PACKAGING
-LEAD FREE-

molex

DOCUMENT NO.: SD-52760-015
SHEET NO.: 1 OF 1

SIZE A4

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